# Package summary

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>package length</td>
<td>-</td>
<td>4.57</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>package diameter</td>
<td>-</td>
<td>3.81</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>actual quantity of termination</td>
<td>-</td>
<td>2</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>
2 Package outline

Hermetically sealed glass package; axial leaded; 2 leads

SOD57

DIMENSIONS (mm are the original dimensions)

<table>
<thead>
<tr>
<th>UNIT</th>
<th>b max.</th>
<th>D max.</th>
<th>G max.</th>
<th>L min.</th>
</tr>
</thead>
<tbody>
<tr>
<td>mm</td>
<td>0.81</td>
<td>3.81</td>
<td>4.57</td>
<td>28</td>
</tr>
</tbody>
</table>

Note
1. The marking band indicates the cathode.

Figure 1. Package outline GALF2 (SOD57)
3 Legal information

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